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Octal Buffers / Drivers with 3-state Outputs



ADE-205-246A (Z)

2nd. Edition Jul. 2001

Description

The HD74LV244A has eight line drivers with three-state outputs in a 20-pin package. Four non-inverters are included in one circuit. Each circuit can be independently controlled by the enable signal $1\overline{OE}$ or $2\overline{OE}$, which enables outputs when receiving a low-level signal. Low-voltage operation is suitable for battery-powered products (e.g., notebook computers), and the low-power consumption extends the battery life.

Features

- $V_{cc} = 2.0 \text{ V}$ to 5.5 V operation
- All inputs V_{IH} (Max.) = 5.5 V (@ V_{CC} = 0 V to 5.5 V)
- All outputs V_0 (Max.) = 5.5 V (@ V_{cc} = 0 V)
- Typical V_{OL} ground bounce < 0.8 V (@ V_{CC} = 3.3 V, Ta = 25°C)
- Typical V_{OH} undershoot > 2.3 V (@ V_{CC} = 3.3 V, Ta = 25°C)
- Output current $\pm 8 \text{ mA}$ (@V_{cc} = 3.0 V to 3.6 V), $\pm 16 \text{ mA}$ (@V_{cc} = 4.5 V to 5.5 V)

Function Table

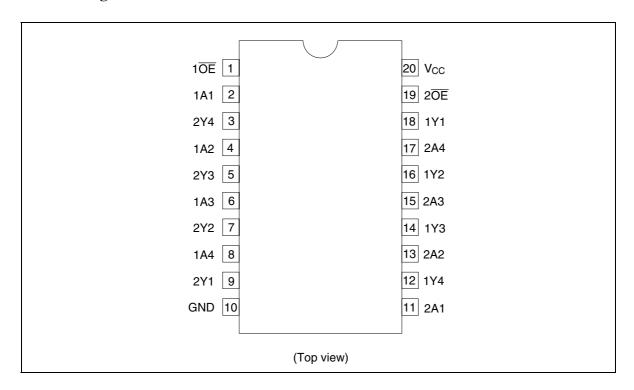
Inputs

ŌE	A	Output Y
L	Н	Н
L	L	L
Н	Х	Z

Note: H: High level

L: Low levelX: ImmaterialZ: High impedance

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage range	V _{cc}	-0.5 to 7.0	V	_
Input voltage range*1	V _i	-0.5 to 7.0	V	
Output voltage range*1, *2	V _o	-0.5 to $V_{cc} + 0.5$	V	Output: H or L
		-0.5 to 7.0	=	V _{cc} : OFF or Output: Z
Input clamp current	I _{IK}	-20	mA	V ₁ < 0
Output clamp current	I _{ok}	±50	mA	$V_o < 0 \text{ or } V_o > V_{cc}$
Continuous output current	I _o	±35	mA	$V_{o} = 0$ to V_{cc}
Continuous current through V_{cc} or GND	I _{CC} or I _{GND}	±70	mA	
Maximum power dissipation at Ta = 25°C (in still air)*3	P _T	835	mW	SOP
		757	=	TSSOP
Storage temperature	Tstg	-65 to 150	°C	

Notes: The absolute maximum ratings are values which must not be individually be exceeded, and furthermore, no two of which may be realized at the same time.

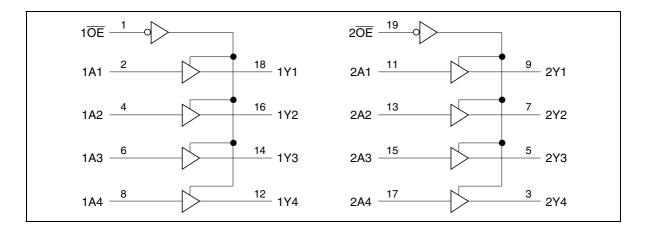
- 1. The input and output voltage ratings may be exceeded even if the input and output clampcurrent ratings are observed.
- 2. This value is limited to 5.5 V maximum.
- 3. The data above are measured by $\Delta V_{_{BE}}$ method mounting on glass epoxy board (40 \times 40 \times 1.6 mm) with 10% of wiring density.

Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage range	V _{cc}	2.0	5.5	V	
Input voltage range	V _i	0	5.5	V	
Output voltage range	V _o	0	V _{cc}	V	H or L
		0	5.5		High impedance state
Output current	I _{OH}	_	-50	μΑ	V _{cc} = 2.0 V
		_	-2	mA	$V_{cc} = 2.3 \text{ to } 2.7 \text{ V}$
		_	-8		$V_{cc} = 3.0 \text{ to } 3.6 \text{ V}$
		_	-16		$V_{cc} = 4.5 \text{ to } 5.5 \text{ V}$
	I _{OL}	_	50	μΑ	V _{cc} = 2.0 V
		_	2	mA	$V_{cc} = 2.3 \text{ to } 2.7 \text{ V}$
		_	8		$V_{cc} = 3.0 \text{ to } 3.6 \text{ V}$
		_	16		$V_{cc} = 4.5 \text{ to } 5.5 \text{ V}$
Input transition rise or fall rate	Δt /Δν	0	200	ns/V	$V_{cc} = 2.3 \text{ to } 2.7 \text{ V}$
		0	100		$V_{cc} = 3.0 \text{ to } 3.6 \text{ V}$
		0	20		$V_{cc} = 4.5 \text{ to } 5.5 \text{ V}$
Operating free-air temperature	Та	-40	85	°C	

Note: Unused or floating inputs must be held high or low.

Logic Diagram



DC Electrical Characteristics

 $Ta = -40 \text{ to } 85^{\circ}\text{C}$

Item	Symbol	V _{cc} (V)*	Min	Тур	Max	Unit	Test Conditions
Input voltage	V _{IH}	2.0	1.5	_	_	٧	_
		2.3 to 2.7	$V_{cc} \times 0.7$	_	_	_	
		3.0 to 3.6	$V_{cc} \times 0.7$	_	_	_	
		4.5 to 5.5	$V_{cc} \times 0.7$	_	_	_	
	V _{IL}	2.0	_	_	0.5	_	
		2.3 to 2.7	_	_	$V_{cc} \times 0.3$	_	
		3.0 to 3.6	_	_	$V_{cc} \times 0.3$	_	
		4.5 to 5.5	_	_	$V_{cc} \times 0.3$	_	
Output voltage	$V_{_{\mathrm{OH}}}$	Min to Max	V _{cc} – 0.1	_	_	V	$I_{OH} = -50 \mu A$
		2.3	2.0	_	_	_	I _{OH} = -2 mA
		3.0	2.48	_	_	_	I _{OH} = -8 mA
		4.5	3.8	_	_	_	I _{OH} = -16 mA
	V _{oL}	Min to Max	_	_	0.1	_	I _{oL} = 50 μA
		2.3	_	_	0.4	_	I _{OL} = 2 mA
		3.0	_	_	0.44	_	I _{OL} = 8 mA
		4.5	_	_	0.55	_	I _{OL} = 16 mA
Input current	I _{IN}	0 to 5.5	_	_	±1	μΑ	V _{IN} = 5.5 V or GND
Off-state output current	l _{oz}	5.5	_	_	±5	μА	$V_o = V_{cc}$ or GND
Quiescent supply current	I _{cc}	5.5	_	_	20	μА	$V_{IN} = V_{CC}$ or GND, $I_{O} = 0$
Output leakage current	OFF	0	_	_	5	μА	$V_{_{\rm I}}$ or $V_{_{\rm O}}$ = 0 V to 5.5 V
Input capacitance	C _{IN}	3.3	_	2.3	_	pF	V _i = V _{cc} or GND

Note: For conditions shown as Min or Max, use the appropriate values under recommended operating conditions.

Switching Characteristics

 $V_{cc} = 2.5 \pm 0.2 \text{ V}$

		Ta = 2	25°C		Ta = -40 to 85°C					
Item	Symbol	Min	Тур	Max	Min	Max	Unit	Test Conditions	FROM (Input)	TO (Output)
Propagation delay time	t _{PLH} t _{PHL}	_	7.5	12.5	1.0	15.0	ns	C _L = 15 pF	Α	Υ
		_	9.5	15.3	1.0	18.0	_	C _L = 50 pF	•	
Enable time	t _{zH} t _{zL}	_	8.9	14.6	1.0	17.0	ns	C _L = 15 pF	ŌĒ	Y
		_	10.8	17.8	1.0	21.0	_	C _L = 50 pF	•	
Disable time	t _{HZ} t _{LZ}	_	9.1	14.1	1.0	16.0	ns	C _L = 15 pF	ŌĒ	Y
		_	13.4	19.2	1.0	21.0	_	C _L = 50 pF	•	

 $V_{cc} = 3.3 \pm 0.3 \text{ V}$

		Ta = 2	25°C		Ta = −40 to 85°C					
Item	Symbol	Min	Тур	Max	Min	Max	Unit	Test Conditions	FROM (Input)	TO (Output)
Propagation delay time	t _{plH} t _{pHL}	_	5.4	8.4	1.0	10.0	ns	C _L = 15 pF	Α	Υ
		_	6.8	11.9	1.0	13.5	_	C _L = 50 pF	='	
Enable time	t _{zh} t _{zL}	_	6.3	10.6	1.0	12.5	ns	C _L = 15 pF	ŌĒ	Υ
		_	7.8	14.1	1.0	16.0	_	C _L = 50 pF	='	
Disable time	t _{HZ} t _{LZ}	_	7.6	11.7	1.0	13.0	ns	C _L = 15 pF	ŌĒ	Υ
		_	11.0	16.0	1.0	18.0	_	C _L = 50 pF		

Switching Characteristics (cont)

 $V_{cc} = 5.0 \pm 0.5 \text{ V}$

		Ta =	25°C		Ta = -40 to 85° C					
Item	Symbol	Min	Тур	Max	Min	Max	Unit	Test Conditions	FROM (Input)	TO (Output)
Propagation delay time	t _{plH} t _{pHL}	_	3.9	5.5	1.0	6.5	ns	C _L = 15 pF	Α	Υ
		_	4.9	7.5	1.0	8.5	="	C _L = 50 pF	_	
Enable time	t _{zh} t _{zL}	_	4.5	7.3	1.0	8.5	ns	C _L = 15 pF	ŌĒ	Υ
		_	5.6	9.3	1.0	10.5	-	C _L = 50 pF	_	
Disable time	t _{HZ}	_	6.5	12.2	1.0	13.5	ns	C _L = 15 pF	ŌĒ	Y
		_	8.8	14.2	1.0	15.5	-	C _L = 50 pF	_	

Output-skew characteristics

 $C_L = 50 \text{ pF}$

			Ta = 25°C		Ta = -40 to	85°C	
Item	Symbol	V_{cc} (V)	Min	Max	Min	Max	Unit
Output skew	t _{sk (O)}	2.3 to 2.7	_	2.0	_	2.0	ns
		3.0 to 3.6	_	1.5	_	1.5	-
		4.5 to 5.5	_	1.0	_	1.0	_

Note: Skew between any outputs of the same package switching in the same direction. This parameter is warranted but not production tested.

Operating Characteristics

 $C_L = 50 \text{ pF}$

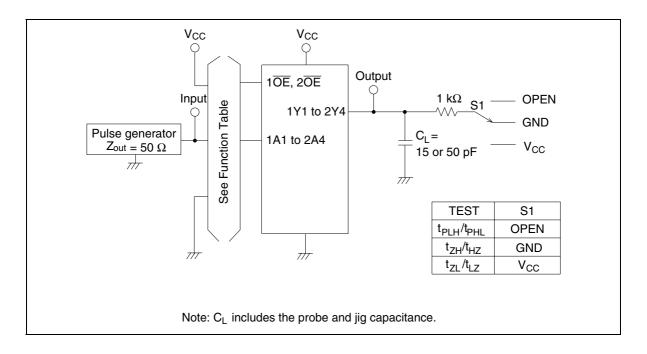
			Ta = 25	s°C			
Item	Symbol	$V_{cc}(V)$	Min	Тур	Max	Unit	Test Conditions
Power dissipation capacitance	C_{\scriptscriptstylePD}	3.3	_	14.0	_	pF	f = 10 MHz
		5.0	_	16.0	_		

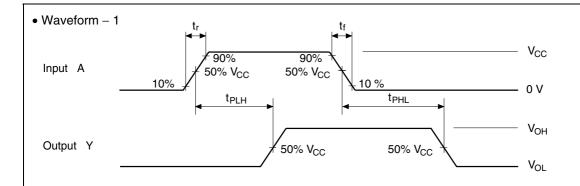
Noise Characteristics

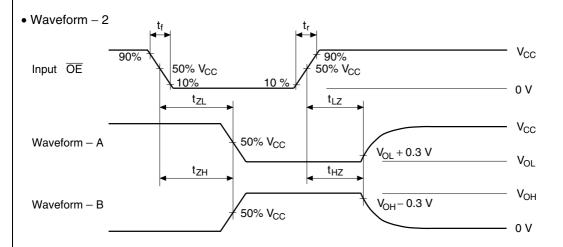
 $C_L = 50 \text{ pF}$

			Ta = 25	°C			
Item	Symbol	V_{cc} (V)	Min	Тур	Max	Unit	Test Conditions
Quiet output, maximum dynamic V _{oL}	$V_{_{OL(P)}}$	3.3	_	0.6	0.8	V	
Quiet output, minimum dynamic V _{OL}	$V_{OL(V)}$	3.3	_	-0.5	-0.8		
Quiet output, minimum dynamic V _{OH}	$V_{_{\mathrm{OH}(V)}}$	3.3	_	2.9	_		
High-level dynamic input voltage	$V_{_{IH\;(D)}}$	3.3	2.31	_	_	V	
Low-level dynamic inout voltage	V _{IL (D)}	3.3	_	_	0.99		

Test Circuit



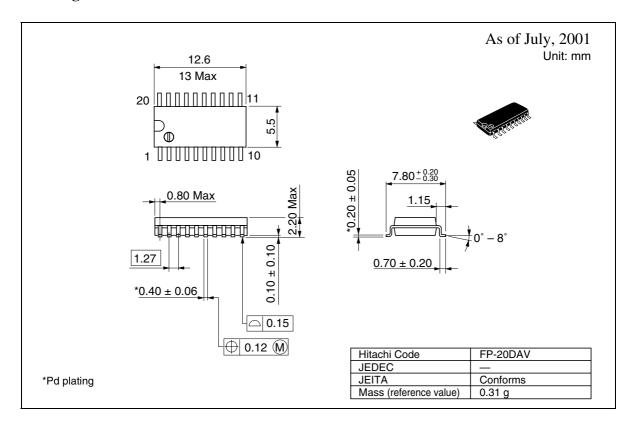


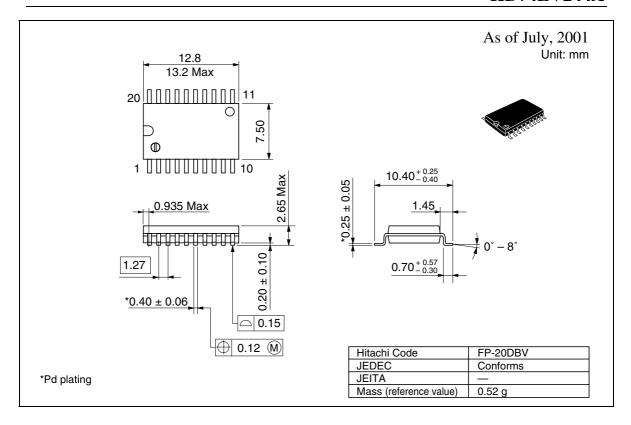


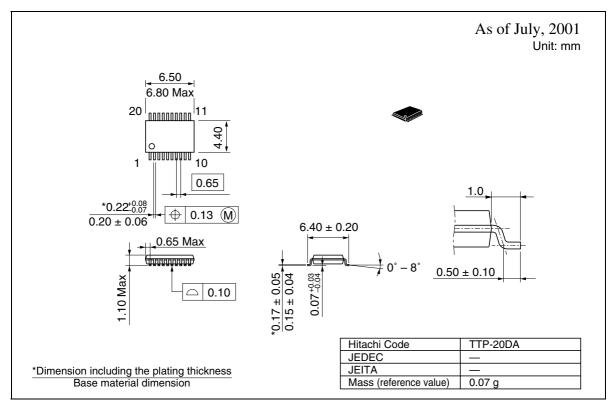
Notes: 1. Input waveform: PRR \leq 1 MHz, Zo = 50 Ω , $t_r \leq$ 3 ns, $t_f \leq$ 3 ns

- 2. Waveform—A is for an output with internal conditions such that the output is low except when disabled by the output control.
- 3. Waveform—B is for an output with internal conditions such that the output is high except when disabled by the output control.
- 4. The output are measured one at a time with one transition per measurement..

Package Dimensions







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